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UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Tongbi Jiang

Serial No.: 09/543,034

Filed: April 5, 2000

For: TAPE ATTACHMENT CHIP-ON-BOARD
ASSEMBLIES AND METHODS OF
FABRICATING THE SAME

Examiner: D. Kang

Group Art Unit: 2811

Attorney Docket No.: 3818.1US (98-0887.1)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail (under 37 C.F.R. § 1.8(a)) on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

June 19, 2002
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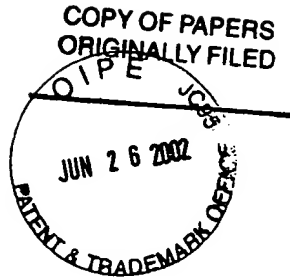
SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
Washington, D.C. 20231

Sir:

In compliance with the duty to disclose information material to patentability pursuant to 37 C.F.R. § 1.56, it is respectfully requested that this Supplemental Information Disclosure Statement be entered and the documents listed on attached Form PTO-1449 or PTO/SB/08A be considered by the Examiner and made of record. The listed documents are from co-pending application Serial No. 09/223,059, filed December 30, 1998. Copies of the listed documents are enclosed pursuant to 37 C.F.R. § 1.98(a).

In accordance with 37 C.F.R. § 1.97(g) and (h), filing of this Supplemental Information Disclosure Statement is not to be construed as a representation that a search has been made or an admission that the information cited herein is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56(b). Further, no representation is made by Applicant herein that no other possible material information as defined in 37 C.F.R. § 1.56(b) exists.



Serial No. 09/543,034

DOCUMENTS

U.S. Patent Documents

<u>U.S. Patent No.</u>	<u>Issue Date</u>	<u>Inventor</u>
6,175,159	01/2001	Sasaki
6,252,298	06/2001	Lee et al.
6,326,700	12/2001	Bai et al.
6,331,453	12/2001	Bolken et al.

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Applicant offers to supply any explanation or discussion of the documents which the Examiner feels is necessary or desirable and which is requested.

This Supplemental Information Disclosure Statement is filed after the mailing date of the final Office Action under 37 C.F.R. § 1.113, but before payment of the issue fee. I hereby certify that no item of information contained in the Supplemental Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned after making reasonable inquiry, was known to any individual designated in 37 C.F.R. § 1.56(c) more than three months prior to the filing of the statement. Pursuant to 37 C.F.R. § 1.97(d)(ii), applicant hereby requests consideration of the accompanying Supplemental Information Disclosure Statement.

Respectfully submitted,

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Date: June 19, 2002

JRD/sls:djp

Enclosures: Form PTO-1449 or PTO/SB/08A
Copy of documents cited